



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TO-220

| Stress | Sample Size | Device Hr./Cyc | Condition | Total Fails | Fail Percentage |
|---------------|--------------------|-----------------------|---------------------------|--------------------|------------------------|
| BOND INT | 360 | 180,000 | 200°C + N2 | 0 | 0.00 |
| HAST | 1,631 | 160,950 | 130°C, 85%RH | 0 | 0.00 |
| Power Cycle | 801 | 7,332,008 | DELTA T _j =100 | 0 | 0.00 |
| Pressure Pot | 4,042 | 388,032 | 121°, 15 PSIG | 0 | 0.00 |
| Solder DUNK | 480 | 1,440 | 260C, 10SEC | 0 | 0.00 |
| Solderability | 390 | 3,600 | 883 M2003 | 0 | 0.00 |
| Temp Cycle | 4,060 | 1,963,000 | -65°C-150°C | 0 | 0.00 |
| Thermal Shock | 1,500 | 150,000 | -60°C-150°C | 0 | 0.00 |